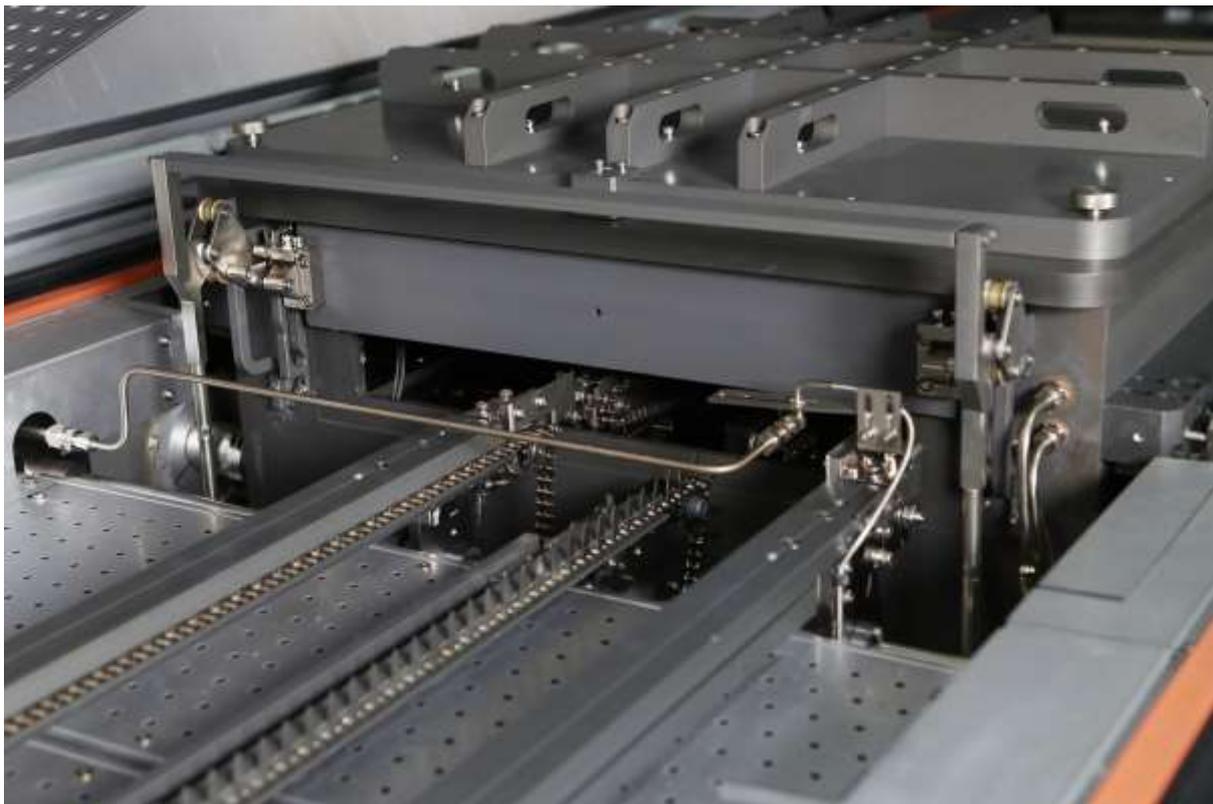




Heller to Unveil New Nitrogen Vacuum Reflow Oven at SMT Nuremberg.

Premier oven innovation company, Heller Industries, will showcase its latest reflow oven on stand 251 in Hall 4 at this year's SMT Hybrid Packaging event in Nuremberg. The company's new 1911MkIII-V Nitrogen Vacuum reflow oven comprises 11 zones, a vacuum chamber, closed-loop nitrogen atmosphere control and Heller's award-winning COOL-PIPE flux management system. This is the first public showing of the new 1911MkIII-V in Europe.



Heller's vacuum reflow chamber, as deployed in the new 1911MkIII-V oven.

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Of the oven's 11 zones, ten deliver convection heating with one infra-red (IR) zone located strategically inside the oven's vacuum chamber. This delivers proven advantages in voidless solder paste reflow processing, leading to long-term solder joint reliability.

The 1911MkIII-V delivers on ambitious performance metrics to help manufacturers streamline SMT assembly. It targets voiding ratios of less than 2% and cycle times of 40 seconds for single-lane implementation and 20 seconds for dual-lane systems. It maintains Heller's solder paste reflow specification, including liquidous times of under 60 seconds. In addition, the oven is suitable for high temperature applications up to 400°C.

"This new model is our most flexible oven to date for vacuum reflow processes. It is aimed at manufacturers looking to drive assembly quality up for challenging products," says Joe Balackyi, Sales Manager at Heller. "Reflow with vacuum significantly reduces void levels to offer high joint integrity. This is a key objective in applications like automotive, power modules and LED manufacture, where a solder joint's efficiency in transmitting power is critical to the subassembly's performance. In this area, the 1911MkIII-V delivers spectacularly," he claims.

Heller Industries is exhibiting its new oven in collaboration with Europlacer, occupying a shared booth at the SMT Hybrid Packaging event in Nuremberg from 5th to 7th June 2018. Heller will also be demonstrating its IPC CFX interface live at the show. Visitors can see the 1911MkIII-V and the CFX demo on stand 4-251 and talk to process, technical and application experts from Heller. "This is the first and perhaps only opportunity for industry professionals in Europe to see the new oven and our CFX interface this year," explains Balackyi.

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About Heller Industries

Heller Industries is focused on Leadership in Reflow Oven Technology. The company was founded in 1960 and pioneered convection reflow soldering in the 1980s. Over the years, Heller has partnered with customers to continually refine the systems to satisfy advanced applications requirements. By embracing challenge and change, Heller has earned the position of World Leader in Reflow Technology. The company continues to push the envelope of leadership in oven technology, providing solutions for electronics manufacturers and assemblers worldwide. Heller Industries is ISO9001 certified company-wide.

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